## N-Channel Super Junction Power MOSFET III

#### **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

#### Features

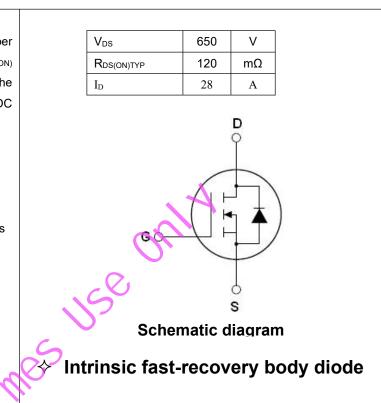
- Optimized body diode reverse recovery performance
- Low on-resistance and low conduction losses
- Small package
- Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

#### Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

Device

NCE65TF130T





#### TO-247

Package Marking And Ordering Information

**Device Package** 

TO-247

Table 1. Absolute Maximum Ratings (Tc=2	5℃)	10-247		
Parameter	Symbol	Value	Unit	
Drain-Source Voltage (Vcs=0V)	Vds	650	V	
Gate-Source Voltage (VDs=0V) AC (f>1 Hz)	Vgs	±30	V	
Continuous Drain Current at Tc=25°C	D (DC)	28	А	
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	18	А	
Pulsed drain current <sup>(Note 1)</sup>	DM (pluse)	112	A	
Maximum Power Dissipation(Tc=25℃)	PD	260	W	
Derate above 25°C		2.08	W/°C	
Single pulse avalanche energy (Note 2)	Eas	676	mJ	
Avalanche current <sup>(Note 1)</sup>	I <sub>AR</sub>	5.2	А	
Repetitive Avalanche energy , $t_{AR}$ limited by $T_{jmax}$ (Note 1)	E <sub>AR</sub>	3.2	mJ	

Marking NCE65TF130T



Parameter	Symbol	Value	Unit
Drain Source voltage slope, $V_{DS} \leq 480 V$ ,	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} \leq 480 \text{ V},I_{SD} < I_D$	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	TJ,TSTG	-55+150	°C

\* limited by maximum junction temperature

#### Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	0.48	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

### Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Мах	Unit	
On/off states							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V D=250µA	650			V	
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			3	μA	
Zero Gate Voltage Drain Current(Tc=125℃)	IDSS	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			300	μA	
Gate-Body Leakage Current	lgss	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±100	nA	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	2.6	3.5	4.3	V	
Drain-Source On-State Resistance		V <sub>GS</sub> =10V, I <sub>D</sub> =14A		120	149	mΩ	
Dynamic Characteristics	X						
Input Capacitance	Clss			2070		pF	
Output Capacitance	Coss	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V,		120		pF	
Reverse Transfer Capacitance	Crss	F=1.0MHz		0.5		pF	
Total Gate Charge	Qg	V/ 400V/1 00A		37.5		nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =480V, $I_{D}$ =28A,		13		nC	
Gate-Drain Charge	Q <sub>gd</sub>	- V <sub>GS</sub> =10V		11.5		nC	
Intrinsic gate resistance	R <sub>G</sub>	f = 1 MHz open drain		10		Ω	
Switching times							
Turn-on Delay Time	t <sub>d(on)</sub>			14		nS	
Turn-on Rise Time	tr	V <sub>DD</sub> =380V,I <sub>D</sub> =14A,		12		nS	
Turn-Off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> =2.3Ω,V <sub>GS</sub> =10V		65		nS	
Turn-Off Fall Time	tr			11		nS	
Source- Drain Diode Characteristics		•					
Source-drain current(Body Diode)	I <sub>SD</sub>	T -25°C			28	А	
Pulsed Source-drain current(Body Diode)	Isdm	- T <sub>c</sub> =25°C			112	А	
Forward On Voltage	Vsd	Tj=25°C,I <sub>SD</sub> =28A,V <sub>GS</sub> =0V		0.9	1.2	V	
Reverse Recovery Time	trr			190		nS	
Reverse Recovery Charge	Qrr			2		uC	
Peak Reverse Recovery Current	I <sub>rrm</sub>			21		А	

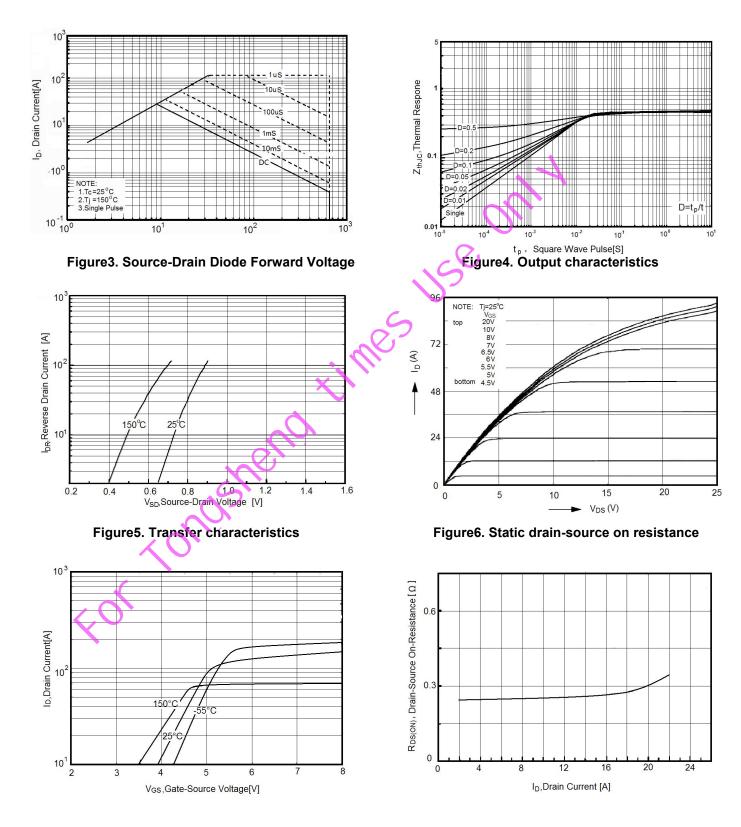
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25  $^\circ\!\mathrm{C}$  ,VDD=50V,VG=10V, R\_G=25\Omega

### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

#### Figure1. Safe operating area

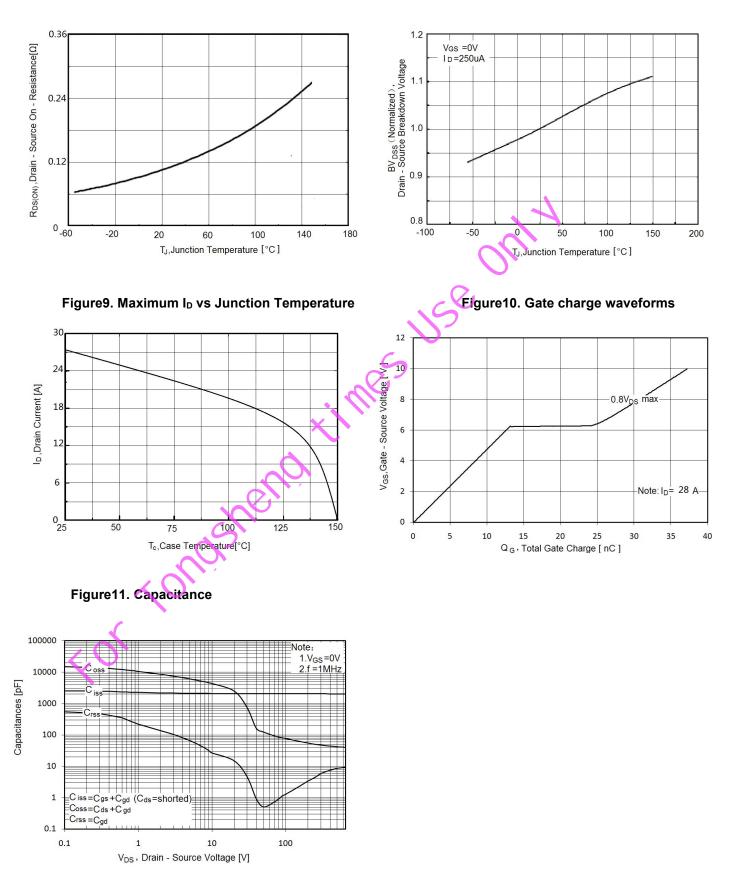
#### Figure2. Transient Thermal Impedance





#### Figure7. R<sub>DS(ON)</sub> vs Junction Temperature

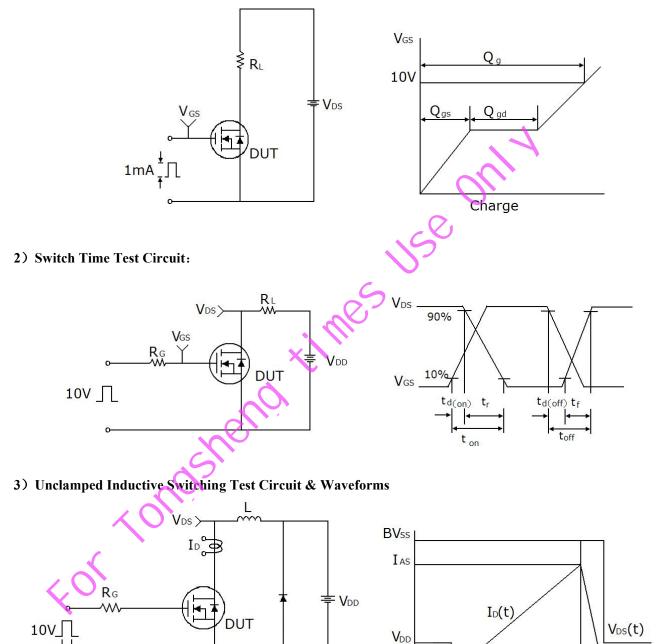
#### Figure8. BV<sub>DSS</sub> vs Junction Temperature





## Test circuit

1) Gate charge test circuit & Waveform



tp

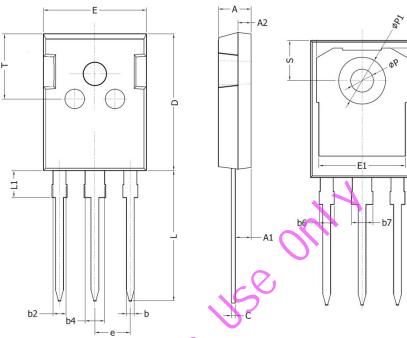
time

►

D2

D1

### TO-247(集佳) Package Information



Symbol	Dimensions In Millimeters		Dimensions	s In Inches
	Min.	Max.	Min.	Max.
А	4.90	5.10	0.193	0.201
A1	2.31	2.51	0.091	0.099
A2	1.90	2.10	0.075	0.083
b	1.16	1.26	0.046	0.050
b2	1.96	2.06	0.077	0.081
b4	2.96	3.06	0.117	0.120
b6		2.25	-	0.089
b7		3.25	-	0.128
С	0.59	0.66	0.023	0.026
D	20.90	21.10	0.823	0.831
D1	16.25	16.85	0.640	0.663
D2	1.05	1.35	0.041	0.053
	15.70	15.90	0.618	0.626
E1	13.10	13.50	0.516	0.531
е	5.436	BSC	0.214	BSC
L	19.80	20.10	0.780	0.791
L1	-	4.30	-	0.169
Р	3.40	3.60	0.134	0.142
P1	7.00	7.40	0.276	0.291
S	6.05	6.25	0.238	0.246
Т	9.80	10.20	0.386	0.402



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